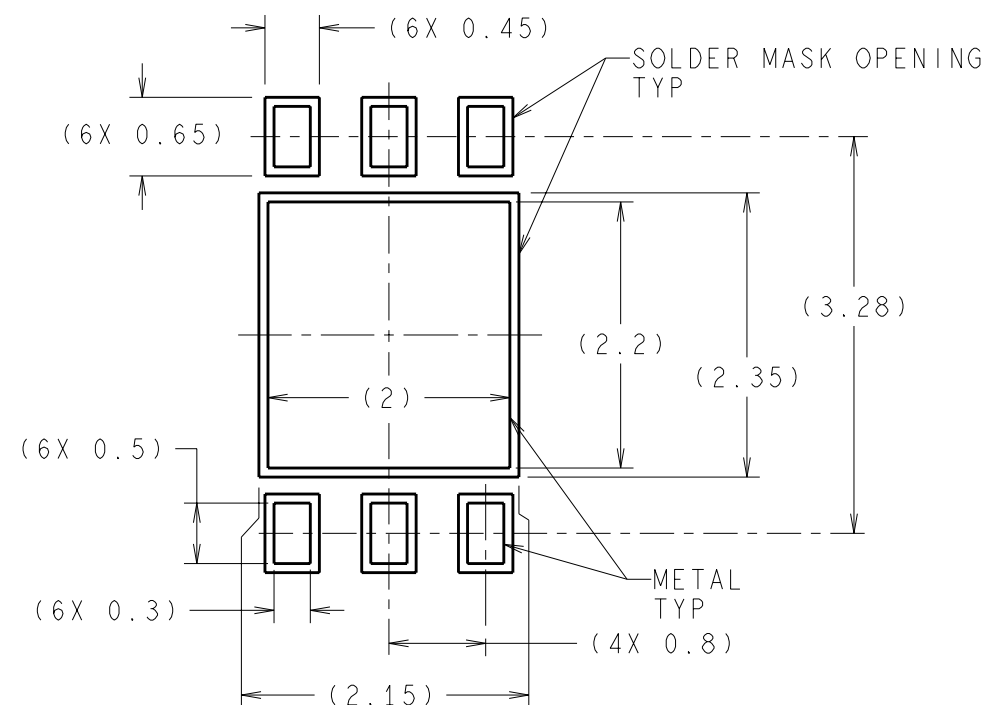
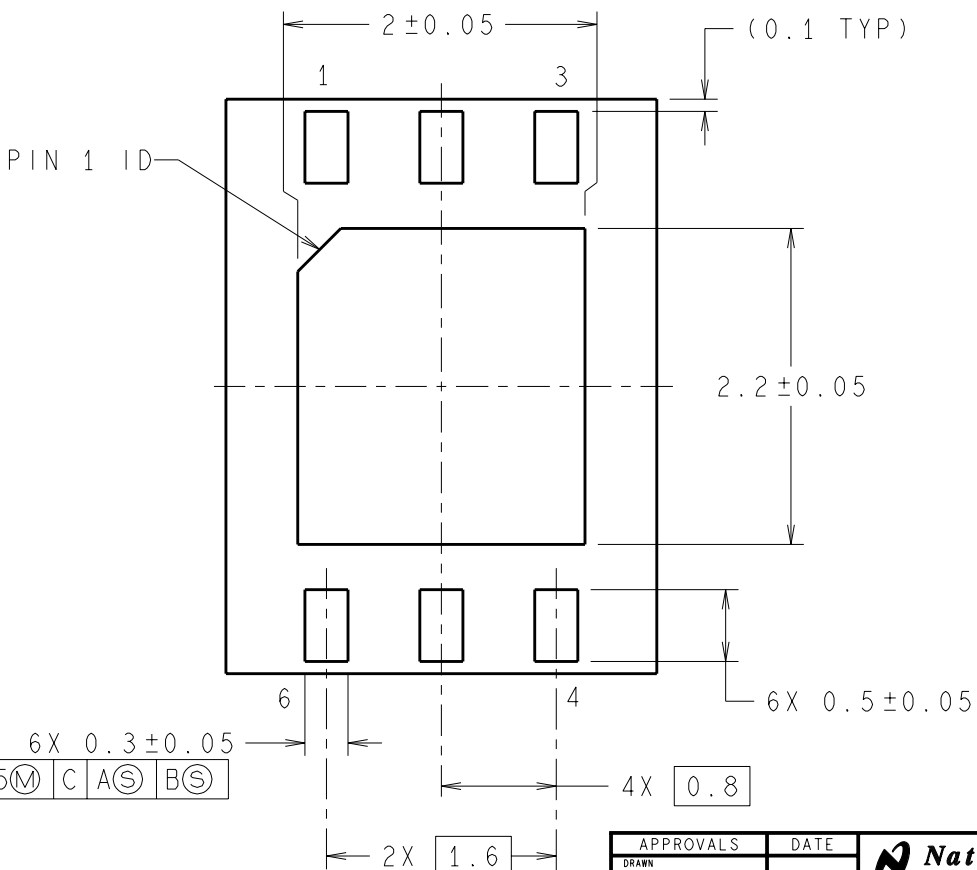
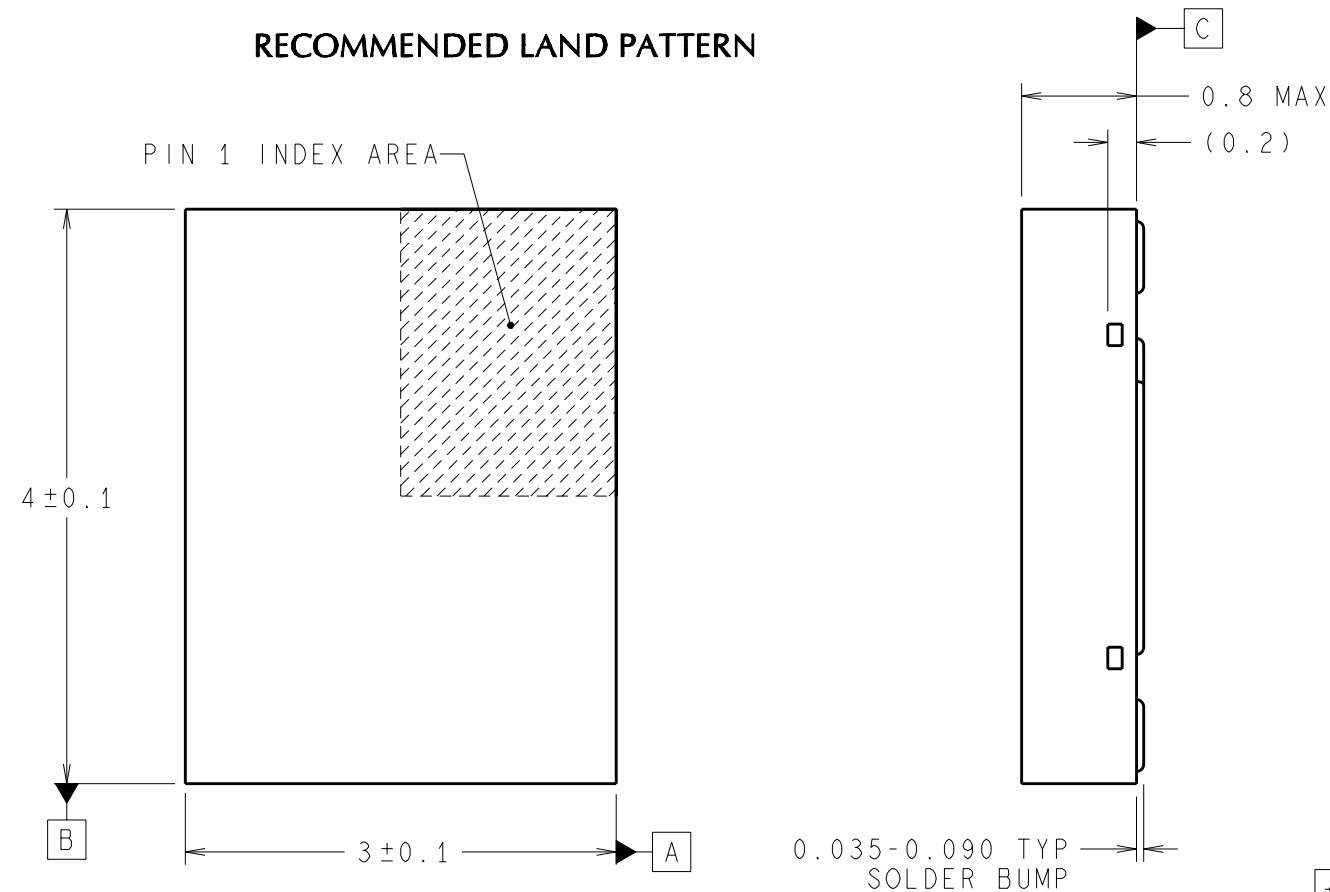


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	995	03/18/2003	TL/JH
B	S/B DIM:0.035-0.090 WAS 0.035 MIN; UPDATE NOTE 2	1068	06/11/2003	TL/JS



RECOMMENDED LAND PATTERN



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR SOLDER COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- NO JEDEC REGISTRATION AS OF JUNE 2003.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	T. LEQUANG	03/18/2003			
DFTG. CHK.	MARTA SUCHY	06/11/2003		LLP, PLASTIC, DUAL, 3x4x0.8mm BODY, 6 LD, 0.8mm PITCH, SOLDER BUMP	
ENGR. CHK.	JEFF SCHAEFER	06/11/2003			
PROJECTION		SCALE		SIZE	DRAWING NUMBER
 MM		NTS		B	(SC)MKT-YDC06B
FORMERLY: N/A		SHEET 1 of 1		REV	B